NPT Trench GBT

1200 V, 25 A

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FGA25N120ANTDTU

Description

Using onsemi's proprietary trench design and advanced NPT Technology, the 1200 V NPT IGBT offers superior conduction and switching performances, high avalanche ruggedness and easy parallel operation. This device is well suited for the resonant or soft switching application such as induction heating, microwave oven.

Features

- NPT Trench Technology, Positive Temperature Coefficient
- Low Saturation Voltage: $V_{CE(sat)}$, typ = 2.0 V @ $I_C = 25$ A and $T_C = 25^{\circ}C$
- Low Switching Loss: $E_{CE \text{ off, typ}} = 0.96 \text{ mJ}$ @ $I_C = 25 \text{ A and } T_C = 25^{\circ}\text{C}$
- Extremely Enhanced Avalanche Capability
- This Device is Pb Free Halide, Free and RoHS Compliant

Applications

• Induction Heating, Microwave OvenC

THERMAL CHARACTERISTICS

| Symbol | Parameter | Value | Unit |
|-----------------------|--------------------------------------|-------|------|
| $R_{\theta JC}(IGBT)$ | Thermal Resistance, Junction to Case | | |

| Symbol | Parameter | Test Cond | Min. | Тур. | Max. | Unit | |
|-----------------|-------------------------------|--|---------------------------------|------|------|------|----|
| V _{FM} | Diode Forward Voltage | I _F = 25 A | $T_{C} = 25^{\circ}C$ | _ | 2.0 | 3.0 | V |
| | | | T _C = 125°C | _ | 2.1 | - | |
| t _{rr} | Diode Reverse Recovery Time | I _F = 25 A, dI _F /dt = 100 A/μs | $T_{C} = 25^{\circ}C$ | - | 235 | 350 | ns |
| | | | T _C = 125°C | - | 300 | - | |
| I _{rr} | Diode Peak Reverse Recovery | | $T_{C} = 25^{\circ}C$ | _ | 27 | 40 | А |
| | Current | | T _C = 125°C | _ | 31 | - | |
| Q _{rr} | Diode Reverse Recovery Charge | | $T_{\rm C} = 25^{\circ}{\rm C}$ | _ | 3130 | 4700 | nC |
| | | | T _C = 125°C | _ | 4650 | _ | |

ELECTRICAL CHARACTERISTICS OF DIODE ($T_C = 25^{\circ}C$ unless otherwise noted)

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

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